

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L1	128079	multilayer	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 16:25	
2	BRS	L2	293	1 and (core adj substrate)	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 17:31	
3	BRS	L3	0	2 and (bonding adj plate)	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 16:40	
4	BRS	L4	167	2 and resin	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 16:40	
5	BRS	L5	11	4 and capacitor	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 16:48	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
6	BRS	L6	42	2 and opening	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 16:47	
7	BRS	L7	6	6 and capacitor	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 16:48	
8	IS&R	L8	2	("6153290").PN.	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 16:52	
9	BRS	L9	13	("4109296" "4811164" "4899118" "5055966" "5315486" "5384434" "5387888" "5416277" "5708559" "5708570" "5757611" "5814366" "6021050").PN.	USPA T	2002/12/29 16:49	
10	BRS	L10	5	6153290.URPN.	USPA T	2002/12/29 16:51	
11	IS&R	L11	2	("5565706").PN.	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 16:59	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
12	BRS	L12	7	("4322778" "4672421" "5049978" "5280192" "5315486" "5331203" "5391917").PN.	USPA T	2002/12/29 16:52	
13	BRS	L13	10	5565706.URPN.	USPA T	2002/12/29 18:02	
14	BRS	L14	12	("4544989" "4993148" "5014111" "5206712" "5262351" "5300812" "5315486" "5508561" "5545589" "5565706" "5757072" "5786628").PN.	USPA T	2002/12/29 16:55	
15	BRS	L15	6	5875100.URPN.	USPA T	2002/12/29 16:56	
16	BRS	L16	30	2 and (thermosetting adj resin)	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 17:31	
17	BRS	L17	41	2 and thermosetting	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 17:06	
18	BRS	L18	24	17 and bond\$3	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 17:06	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
19	BRS	L19	1821	(core adj substrate)	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 17:31	
20	BRS	L20	109	19 and (thermosetting adj resin)	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 17:32	
21	BRS	L21	30	19 and (resin adj layers)	USPA T	2002/12/29 18:06	
22	IS&R	L22	2	("5937493").PN.	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 18:04	
23	BRS	L23	1	"3326718".PN.	USPA T	2002/12/29 18:05	
24	BRS	L25	1	5937493.URPN.	USPA T	2002/12/29 18:05	
25	BRS	L26	69	19 and (resin adj layer)	USPA T	2002/12/29 18:06	
26	BRS	L27	372	19 and laminat\$3	USPA T	2002/12/29 18:06	
27	BRS	L28	239	27 and resin	USPA T	2002/12/29 18:07	
28	BRS	L29	66	28 and (opening or reces or aperture)	USPA T	2002/12/29 18:07	
29	BRS	L30	15	29 and capacitor	USPA T	2002/12/29 18:10	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
30	BRS	L31	18	("5103288" "5498467" "5526449" "5600342" "5731073" "5766979" "5830565" "5886413" "5886535" "5896038" "5966022" "5966593" "5990850" "6046076" "6114087" "6177181" "6216469" "6255601").PN.	USPA T	2002/12/29 18:09	
31	BRS	L32	156	multilayer adj wiring adj board	USPA T	2002/12/29 18:12	
32	BRS	L33	116	32 and resin	USPA T	2002/12/29 18:35	
33	BRS	L34	5	("4617586" "5027253" "6038122" "6094336" "6252761").PN.	USPA T	2002/12/29 18:18	
34	BRS	L35	19	("3326718" "3624895" "3665346" "3699011" "3949275" "4237522" "4328531" "4342143" "4349862" "4453176" "4460938" "4682414" "4705917" "4729061" "4744008" "4751126" "4890192" "4910638" "4958258").PN.	USPA T	2002/12/29 18:19	
35	BRS	L36	35	5027253.URPN.	USPA T	2002/12/29 18:21	
36	BRS	L37	12	19 and (resin adj insulating adj layer)	USPA T	2002/12/29 18:40	
37	BRS	L38	5	("4710593" "4791238" "5675299" "5956843" "6042685").PN.	USPA T	2002/12/29 18:36	
38	BRS	L39	4	("4816323" "5346750" "5766670" "6010768").PN.	USPA T	2002/12/29 18:37	
39	BRS	L40	2	("5590016" "5636099").PN.	USPA T	2002/12/29 18:39	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
40	IS&R	L41	155	(361/763).CCLS.	USPA T; EPO; JPO; DER WEN T; USOC R	2002/12/29 18:40	
41	BRS	L42	6	("4750246" "5103283" "5438305" "5539358" "5798557" "6133674").PN.	USPA T	2002/12/29 18:41	

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DBS USPAT EPO JPO DERWENT USOCR

Highlight all hit terms initially

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257/686 257/725 Kondo, Yoichiro

1 US 6495915 20021217 17 Flip chip package of monolithic microwave interconnect R1
2 US 6495913 20021217 15 Semiconductor clamped-stack assembly R2
3 US 6483188 20021119 6 Rf integrated circuit layout R1
4 US 6476484 20021105 7 Heat sink dissipator for adapting to thickness change R1
5 US 6472748 20021029 9 System and method for providing MMIC seal R1
6 US 6472723 20021029 12 Substrate contacts and shielding devices in a semiconductor device R1
7 US 6469377 20021022 12 Semiconductor device R1

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